

Switching Diode MMBD6050LT1G

Features

 These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Reverse Voltage	V _R	70	Vdc
Forward Current	IF	200	mAdc
Peak Forward Surge Current	I _{FM(surge)}	500	mAdc

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board, (Note 1) T _A = 25°C Derate above 25°C	P _D	225 1.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate, (Note 2) T _A = 25°C Derate above 25°C	P _D	300 2.4	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature	T _J , T _{stg}	-55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. $FR-5 = 1.0 \times 0.75 \times 0.062$ in.
- 2. Alumina = $0.4 \times 0.3 \times 0.024$ in. 99.5% alumina.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Rating	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Reverse Breakdown Voltage (I _(BR) = 100 μAdc)	V _R	70	-	Vdc
Reverse Voltage Leakage Current (V _R = 50 Vdc)	I _R	-	0.1	μAdc
Forward Voltage (I _F = 1.0 mAdc) (I _F = 100 mAdc)	V _F	0.55 0.85	0.7 1.1	Vdc
Reverse Recovery Time (Figure 1) (I _F = I _R = 10 mAdc, I _{R(REC)} = 1.0 mAdc)	t _{RR}	-	4.0	ns
Capacitance (V _R = 0 V)	C _D	-	2.5	pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.





SOT-23 (TO-236) CASE 318 STYLE 8

MARKING DIAGRAM



5A = Device Code M = Date Code*

= Pb-Free Package

(Note: Microdot may be in either location)

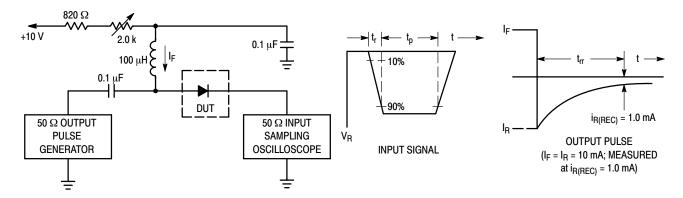
*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]
MMBD6050LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel
MMBD6050LT3G	SOT-23 (Pb-Free)	10,000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MMBD6050LT1G



Notes: 1. A 2.0 $k\Omega$ variable resistor adjusted for a Forward Current (I_F) of 10 mA.

- 2. Input pulse is adjusted so $I_{R(peak)}$ is equal to 10 mA.
- 3. t_p » t_{ri}

Figure 1. Recovery Time Equivalent Test Circuit

TYPICAL CHARACTERISTICS

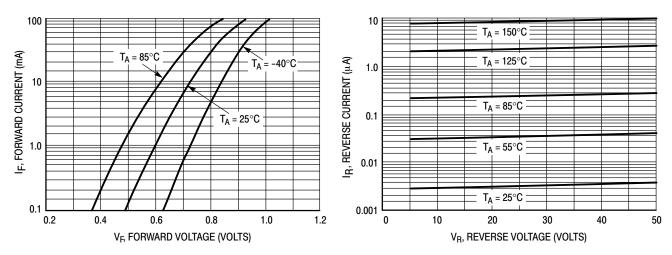


Figure 2. Forward Voltage

Figure 3. Leakage Current

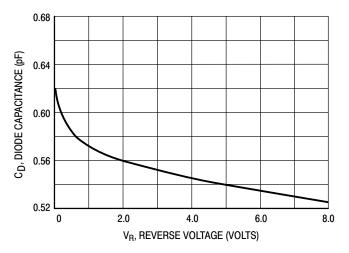


Figure 4. Capacitance

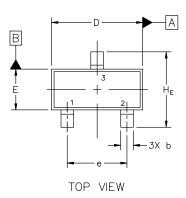


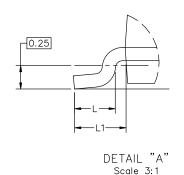


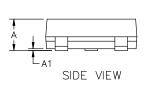
SOT-23 (TO-236) 2.90x1.30x1.00 1.90P CASE 318 ISSUE AU

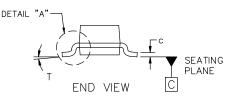
DATE 14 AUG 2024

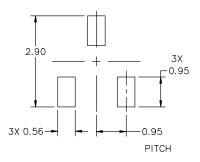
MAX











Α 0.89 1.00 1.11 Α1 0.01 0.06 0.10 0.37 0.50 b 0.44 0.08 0.20 0.14 С D 2.80 2.90 3.04 Ε 1.20 1.30 1.40 1.78 1.90 2.04 е L 0.30 0.43 0.55 L1 0.35 0.54 0.69 HE 2.10 2.40 2.64 Τ O° ___ 10°

MILLIMETERS

MIN

NOM

NOTES:

DIM

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M. 2018.
- PER ASME Y14.5M, 2018.
 2. CONTROLLING DIMENSIONS:
 MILLIMETERS.
- 3. MAXIMUM LEAD THICKNESS
 INCLUDES LEAD FINISH. MINIMUM
 LEAD THICKNESS IS THE
 MINIMUM THICKNESS OF THE
 BASE MATERIAL
- BASE MATERIAL.

 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

M = Date Code

■ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

RECOMMENDED MOUNTING FOOTPRINT

* For additional information on our Pb—Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

STYLES ON PAGE 2

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DATE 14 AUG 2024

STYLE 1 THRU 5: CANCELLED	STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR		NODE D CONNECTION ATHODE	
STYLE 9: PIN 1. ANODE 2. ANODE 3. CATHODE	STYLE 10: PIN 1. DRAIN 2. SOURCE 3. GATE	STYLE 11: STYLE 12: PIN 1. ANODE PIN 1. CA 2. CATHODE 2. CA 3. CATHODE-ANODE 3. AN	ATHODE PIN 1. SOURCE ATHODE 2. DRAIN	STYLE 14: PIN 1. CATHODE 2. GATE 3. ANODE
STYLE 15: PIN 1. GATE 2. CATHODE 3. ANODE	STYLE 16: PIN 1. ANODE 2. CATHODE 3. CATHODE			STYLE 20: PIN 1. CATHODE 2. ANODE 3. GATE
STYLE 21: PIN 1. GATE 2. SOURCE 3. DRAIN	STYLE 22: PIN 1. RETURN 2. OUTPUT 3. INPUT	STYLE 23: STYLE 24: PIN 1. ANODE PIN 1. GAT 2. ANODE 2. DR/ 3. CATHODE 3. SOU	TE PIN 1. ANODE AIN 2. CATHODE	STYLE 26: PIN 1. CATHODE 2. ANODE 3. NO CONNECTION
STYLE 27: PIN 1. CATHODE 2. CATHODE 3. CATHODE	STYLE 28: PIN 1. ANODE 2. ANODE 3. ANODE			

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